Microtron® Printed Circuit Board Fuses .122" x .297" (3.10mm x 7.54mm)

MCR







Actual Size

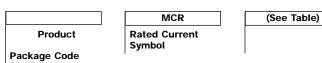
Product Name: MCR (Microtron®)

Characteristics: Fast Acting, Current Limiting

Construction: Solid Matrix

Packaging & Ordering Information:

Dimensional Data *All tolerances: ±0.005" ±0.13mm 28.58mm .12" .297" 7.54mm



Package Co Blank 10 in BK 500 in

0.64mm

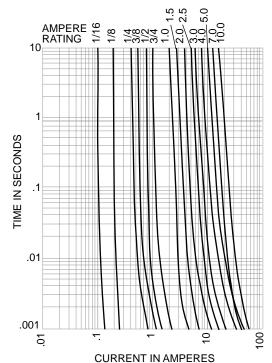
BK 500 in
TR/ Tape/Reel 2500 units, 52.4mm spacing
TR1/ Tape/Reel 5000 units, 52.4mm spacing
TR6/ Tape/Reel 1000 units, 52.4mm spacing
Radial leaded versions available (.4", .6" spacing)

Weight = 2.45 lbs/2500

Time-Current Characteristics:

Rated	Percent of Rating				
Current	100%	250%			
0-10A	4 hrs. (min)	5 sec. (max)			

Time-Current Characteristic Curves-Average Melt (Full Size Curves Available)



CE CE logo denotes compliance with European Union Low Voltage Directive (50-1000 VAC, 75-1500 VDC). Refer to BIF document #8002 or contact Bussmann Application Engineering at 314-527-1270 for more information.

Electrical Characteristics

Current	Rated Voltage		Interrupting Rating ¹		Pre-arcing ² I ² t (A ² sec)		Typical Total Clearing ²		Typical Voltage Drop Volts at	Agency* Approvals		
Rating	AC (Max.)	DC (Max.)	AC AC	DC	AC AC	DC	AC AC	DC	100% Rated Current	품	CSA	SIC
1/16	125V	125V	50A	300A	1.1 × 10 ⁻⁶	1.0 × 10 ⁻⁷	1.8 × 10 ⁻⁶	1.5 × 10 ⁻⁷	2.33	•	•	
1/8	125V	125V	50A	300A	4.3 × 10 ⁻⁶	7.1×10^{-7}	7.3 × 10 ⁻⁶	8.7×10^{-7}	1.52		•	
1/4	125V	125V	50A	300A	8.0 × 10 ⁻⁵	1.0×10^{-6}	1.2 × 10 ⁻⁴	1.3×10^{-6}	.76		•	
3/8	125V	125V	50A	300A	9.7 × 10 ⁻⁵	6.7 × 10 ⁻⁶	1.1 × 10 ⁻⁴	8.3 × 10 ⁻⁶	.73	•	•	
1/2	125V	125V	50A	300A	7.4 × 10 ⁻⁴	5.4×10^{-5}	6.2×10^{-3}	6.8×10^{-5}	.65		•	
3/4	125V	125V	50A	300A	1.3 ×10 ⁻³	7.4×10^{-5}	7.5×10^{-2}	9.2×10^{-5}	.55		•	
1	125V	125V	50A	300A	.01	.01	.02	.01	.24	•	•	•
1½	125V	125V	50A	300A	.03	.02	.04	.03	.20	•	•	•
2	125V	125V	50A	300A	.09	.07	.11	.08	.16		•	•
2½	125V	125V	50A	300A	.19	.14	.25	.17	.15	•	•	•
3	125V	125V	50A	300A	.35	.28	.45	.32	.15	•	•	•
31/2	125V	125V	50A	300A	.56	.37	.83	.43	.14	•	•	•
4	125V	125V	50A	300A	.96	.67	1.37	.77	.13	•	•	•
5	125V	125V	50A	300A	1.82	1.34	2.53	1.51	.11	•	•	•
7	60V	90V	50A	300A	1.48	.49	2.02	.58	.10		•	
10	60V	90V	50A	300A	3.62	1.16	4.41	1.38	.08	•	•	

^{*}Approvals: UL Recognition STD 248-14, Guide JDYX2, File E19180; CSA Certification, Class 1422-01, File 53787. JIS (Japanese Industrial Standard) Reg. No. 2221, Authorization No. 32-1516.

1. Interrupting ratings were measured at 100% (1/16 to 5) and 100% (7, 10) power factors on AC, and a time constant less than 1ms. on D.C.

2. I2t was measured at 50 amps 125 VAC, .95PF, (random closing angle) and 300 amps 125 VDC, TC <1ms. for 1/16 through 5 amps and 50 amps 60 VAC, .95PF, (random closing angle), and 300 amps 90 VDC, TC <1ms. for the 7 and 10 amp fuses.

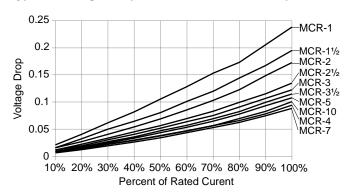
Note: All values shown above are typical.

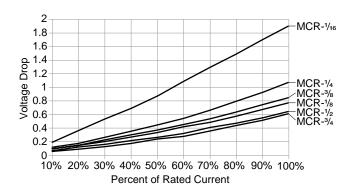
Microtron® Printed Circuit Board Fuses .122" x .297" (3.10mm x 7.54mm)

MCR



Typical Voltage Drop (At 25° C Ambient Temperature)





Microtron fuses are designed to meet the following specifications:

Body High temperature thermoplastic, Resistance flammability rating UL 94 VO. Soldering

Electrical Characteristics Carry 100% rated current for 4 hours

minimum. Open at 250% of rated current in 5 seconds maximum.

Element Solid Matrix, gold or silver element

encapsulated in ceramic.

Leads Tin-plated copper, .64mm (.025")

diameter.

Lead Bend Test With a two pound weight attached, 90°

one direction, back to original position, then 90° opposite direction; fuse will

withstand two cycles.

Life Test 2000 hours at 80% rated current,

55°C.

Moisture Resistance MIL-STD-202, Method 106, 90%

relative humidity at 65°C.

Operating Temperature -55°C to 125°C with proper fuse

derating.

Packaging EIA-STD-296-E.

Resistance to MIL-STD-202, Method 210, Test **Soldering Heat** Condition C (260°C).

idei ing neat Condition C (200 C).

Salt Spray MIL-STD-202, Method 101, Test

Condition B.

Shock MIL-STD-202, Method 213, Test

Condition I, 100G's for 6 milliseconds.

Solderability MIL-STD-202, Method 208.

Terminal Strength MIL-STD-202, Method 211, Test

Condition A, will withstand 7 lb. axial pull

test.

Thermal Shock MIL-STD-202, Method 107, Test

Condition B, -65°C to 125°C.

Thermal Cycle EIA-STD-RS-186-C, Test Condition A,

-55°C to 85°C.

Vibration MIL-STD-202, Method 204, Test

Condition C, (55 to 2000 HZ, 10G's

peak).

Wave Soldering Maximum reservoir temperature 260°C,

10 second maximum exposure, .125"

from body.

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